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Front Matter: Volume 11518

, "Front Matter: Volume 11518," Proc. SPIE 11518, Photomask Technology 2020, 1151801 (16 October 2020); doi: 10.1117/12.2580779

SPIE.

Event: SPIE Photomask Technology + EUV Lithography, 2020, Online Only

PROCEEDINGS OF SPIE

Photomask Technology 2020

Moshe E. Preil

Editor

**21–25 September 2020
Online Only, United States**

Sponsored by

The international technical group of SPIE dedicated
to the advancement of photomask technology

SPIE.

Published by
SPIE

Volume 11518

Proceedings of SPIE 0277-786X, V. 11518

SPIE is an international society advancing an interdisciplinary approach to the science and application of light.

Photomask Technology 2020, edited by Moshe E. Preil, Proc. of SPIE Vol. 11518,
1151801 · © 2020 SPIE · CCC code: 0277-786X/20/\$21 · doi: 10.1117/12.2580779

Proc. of SPIE Vol. 11518 1151801-1

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Author(s), "Title of Paper," in *Photomask Technology 2020*, edited by Moshe E. Preil, Proceedings of SPIE Vol. 11518 (SPIE, Bellingham, WA, 2020) Seven-digit Article CID Number.

ISSN: 0277-786X

ISSN: 1996-756X (electronic)

ISBN: 9781510638433

ISBN: 9781510638440 (electronic)

Published by

SPIE

P.O. Box 10, Bellingham, Washington 98227-0010 USA

Telephone +1 360 676 3290 (Pacific Time) · Fax +1 360 647 1445

SPIE.org

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